**Supplementary Material**

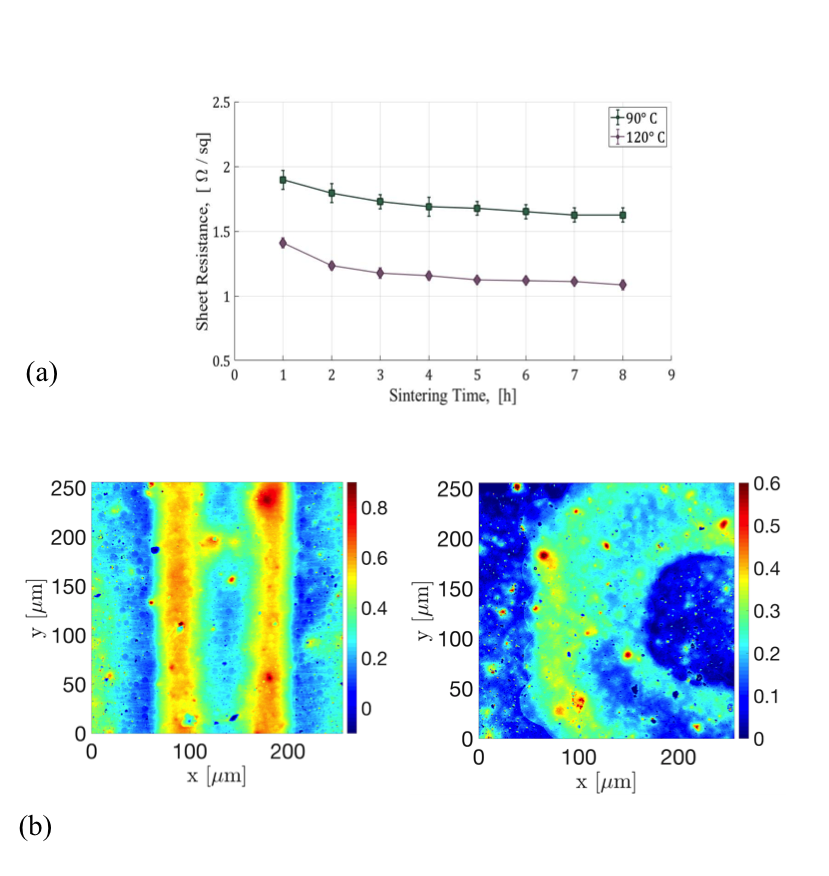
Reliability of inkjet printed silver nanoparticle interconnects on deformable substrates tested through an electromechanical in-situ technique

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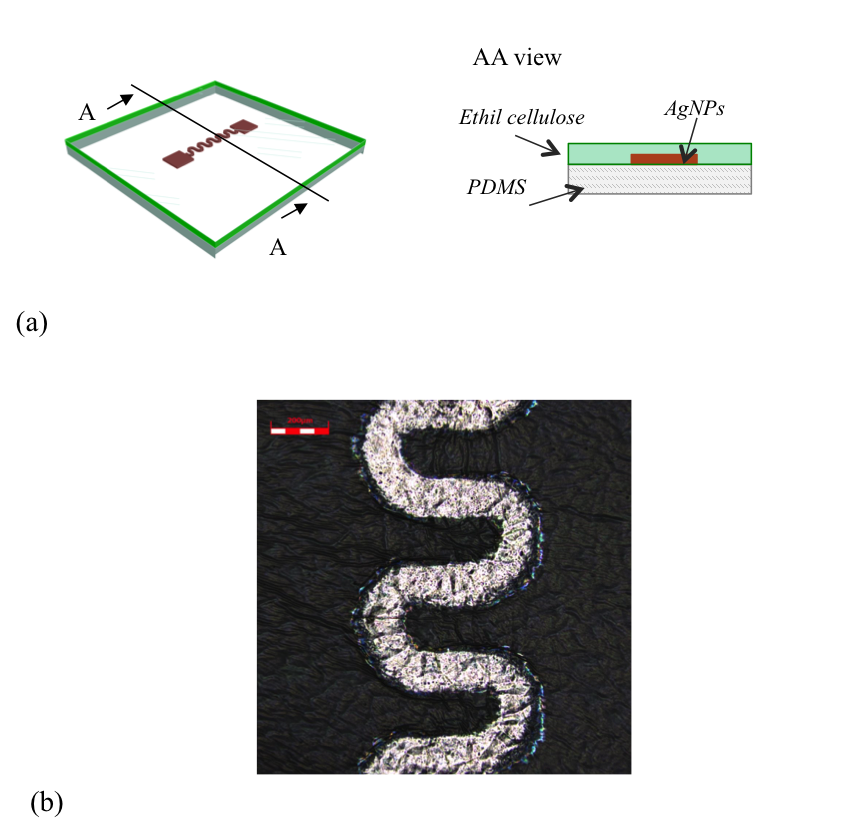
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| S.1 (a) Sheet resistance as a function of the sintering temperature and time of AgNPs inkjet printed line. (b) Height contrast images of the (left) linear and (right) serpentine interconnect on PET substrate. |

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| S.2 (a) (left) Schematic representation of the PDMS interconnect made using tattoo paper. (right) Cross section view of the three layers structure: Ethyl cellulose (EC) film, printed AgNPs track, and PDMS. (b) CLM colour image of the interconnect after transfer on PDMS. |



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| S.3 (a) CLM colour image of the inkjet printed (EC/AgNPs/PDMS) interconnect at 10% strain (b) magnification of the interconnect meander at (left) 0% and (right) 4% strain. |

